



# Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

Adobe Reader version 7.0.5 is required to complete this declaration.

1752-2 1.1	IPC Web Site for Information on IPC-1752 Standard <a href="http://www.ipc.org/IPC-175x">http://www.ipc.org/IPC-175x</a>	Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Informat
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## Supplier Information

Company Name * IDT	Company Unique ID	Unique ID Authority	Response Date * 2012-10-22	Response Document ID NBG24 Copper Wire				
Contact Name * CS Phek	Title - Contact Engineer	Phone - Contact * 604-613-2538	Email - Contact * csphek@idt.com	<input type="button" value="Duplicate Contact -&gt; Authorized Representative"/>				
Authorized Representative * CS Phek	Title - Representative Engineer	Phone - Representative * 604-613-2538	Email - Representative * csphek@idt.com	Supplier Comments or URL for Additional Information				
Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	Version	Manufacturing Site	Weight *	UOM	Unit Type
		NBG24 Copper Wire	2012-10-22	0	Amkor	37.04	mg	Each
Alternate Recommendation				Alternate Item Comments				

## Manufacturing Process Information

Terminal Plating / Grid Array Material <b>Matte Tin (Sn) - annealed</b>	Terminal Base Alloy <b>CU Alloy</b>	J-STD-020 MSL Rating <b>1</b>	Peak Process Body Temperature <b>260 C</b>	Max Time at Peak Temperature <b>30 seconds</b>	Number of Reflow Cycles <b>3</b>
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Comments

Save the fields in this form to a file

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Lock Supplier Fields

## RoHS Material Composition Declaration

Declaration Type \*

Simplified

**RoHS Directive 2002/95/EC** **RoHS Definition:** Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Supplier certifies that it gathered the information it provides in this form concerning RoHS restrictive substances using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

**RoHS Declaration \*** 1 - Item(s) does not contain RoHS restricted substances per the definition above

**Supplier Acceptance \*** Accepted

**Exemptions:** If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.

## Declaration Signature

**Instructions:** Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.

Supplier Digital Signature

## Homogeneous Material Composition Declaration for Electronic Products

**SubItem Instructions:** The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

**Substance Instructions:** [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

**Line Functions:** +I Inserts a New Item /SubItem +M Inserts a new Material +C Inserts a new Substance Category +S Inserts a new Substance - Deletes the element line

+I	-I	Item/SubItem Name	+M	-M	Homogeneous Material	Weight	Unit of Measure	+C	-C	Level	Substance Category	+S	-S	Substance	CAS	Exempt	Weight	Unit of Measure	Tolerance		PPM
																			-	+	
		NBG24 Copper Wire			Mold Compound	20.235	mg			Supplier	Filler			Fused Silica	60676-86-0		17.6044	mg	0.02	0.02	475,28
										Supplier	Binder			Epoxy Resin	Trade Secre		1.5176	mg			40,973
										Supplier	Binder			Phenol Resin	Trade Secre		1.0117	mg			27,315
										Supplier	Coloring			Carbon Black	1333-86-4		0.1012	mg			2,732
					Die Attach Adhes	0.3371	mg			Supplier	Filler			Silver	7440-22-4		0.2848	mg			7,690
										Supplier	Binder			Epoxy Resin A	9003-36-5		0.0202	mg			546
										Supplier	Binder			Epoxy Resin B	Trade Secre		0.0202	mg			546
										Supplier	Binder			Diluent	3101-60-8		0.0101	mg			273
										Supplier	Binder			Dicyandiamide	461-58-5		0.0017	mg			46
					Lead Frame	14.5604	mg			Supplier	Copper Alloy			Copper	7440-50-8		13.5657	mg			366,24
										Supplier	Copper Alloy			Iron	7439-89-6		0.3053	mg			8,243
										Supplier	Copper Alloy			Phophorus	7723-14-0		0.0022	mg			59
										Supplier	Copper Alloy			Zinc	7440-66-6		0.0073	mg			197
										A	Lead/Lead Compound			Lead	7439-92-1		0.0044	mg			118
										Supplier	Plating			Nickel (Use internal onl	7440-02-0 (u		0.3407	mg			9,198
										Supplier	Plating			Palladium	7440-05-3		0.1456	mg			3,931
										Supplier	Plating			Silver	7440-22-4		0.1165	mg			3,145
										Supplier	Plating			Gold	7440-57-5		0.0728	mg			1,965
					Lead Finish	1.1001	mg			Supplier	Solder Plating			Tin	7440-31-5		1.1001	mg			29,700
					Bond Wire	0.0296	mg			Supplier	Wire			Copper	7440-50-8		0.0288	mg			778
										Supplier	Coating			Palladium	7440-05-3		0.0008	mg			22
					Silicon	0.7778	mg			Supplier	Silicon Chip			Silicon	7440-21-3		0.7778	mg			21,000